

STRUCTURE	Silicon monolithic integrated circuits
PRODUCT SERIES	Bipolar stepping motor driver
TYPE	BD63940EFV
FUNCTION	<ul style="list-style-type: none"> • PWM constant current controllable two H bridge driver • Forward, Reverse, Brake mode • Parallel IN control

○Absolute maximum ratings(Ta=25°C)

Item	Symbol	Limit	Unit
Supply voltage	V _{CC1,2}	-0.2~+36.0	V
Power dissipation	Pd	1.1 ^{※1}	W
		4.0 ^{※2}	W
Input voltage for control pin	V _{IN}	-0.2~+5.5	V
RNF maximum voltage	V _{RNF}	0.5	V
Maximum output current	I _{OUT}	1.2 ^{※3}	A/phase
Operating temperature range	T _{opr}	-25~+85	°C
Storage temperature range	T _{stg}	-55~+150	°C
Junction temperature	T _{jmax}	+150	°C

※1 70mm × 70mm × 1.6mm glass epoxy board. Derating in done at 8.8mW/°C for operating above Ta=25°C.

※2 4-layer recommended board. Derating in done at 32.0mW/°C for operating above Ta=25°C.

※3 Do not, however exceed Pd, ASO and Tjmax=150°C.

○Recommended operating conditions (Ta=-25~+85°C)

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	V _{CC1,2}	19	24	28	V
Output current	I _{OUT}	-	0.7	0.9 ^{※4}	A/phase

※4 Do not, however exceed Pd, ASO.

This product isn't designed for protection against radioactive rays.

Status of this document

The Japanese version of this document is the formal specification.

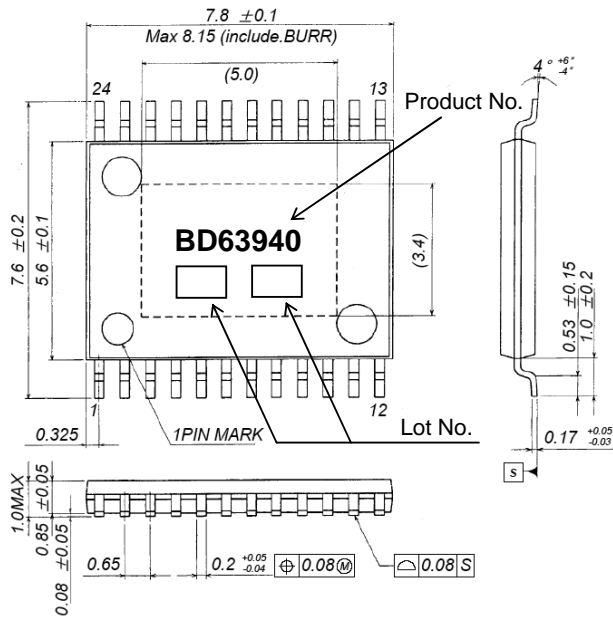
A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document, formal version takes priority.

○Electrical characteristics (Unless otherwise specified Ta=25°C, VCC1,2=24V)

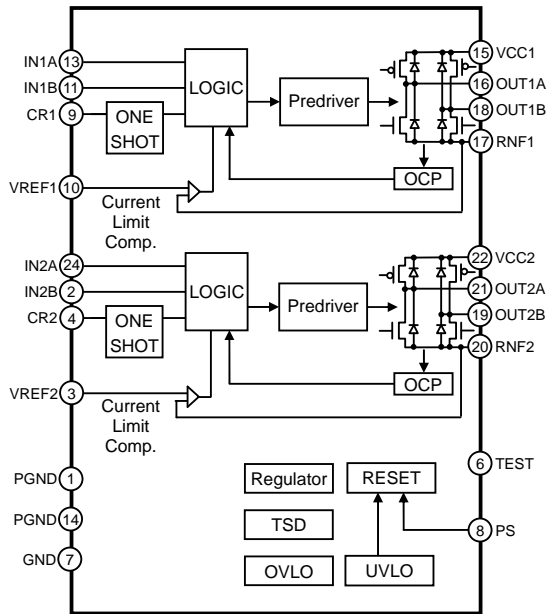
Item	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
Whole						
Circuit current at standby	I _{CCST}	-	0.6	2.0	mA	PS=L
Circuit current	I _{CC}	-	2.7	7.0	mA	PS=H, VREFX=0.4V
Control input (IN1A, IN1B, IN2A, IN2B, PS)						
H level input voltage	V _{INH}	2.0	-	-	V	
L level input voltage	V _{INL}	-	-	0.8	V	
Output (OUT1A, OUT1B, OUT2A, OUT2B)						
Output ON resistance	R _{ON}	-	1.4	1.8	Ω	I _{OUT} =0.7A, Sum of upper and lower
Output leak current	I _{LEAK}	-	-	10	μA	
Current control						
RNFX input current	I _{RNF}	-40	-20	-	μA	RNFX=0V
VREFX input current	I _{VREF}	-2.0	-0.1	-	μA	VREFX=0V
VREFX input voltage range	V _{REF}	0	-	0.4	V	
Comparator offset	V _{COF}	-20	0	20	mV	VREFX=0.4V
Minimum on time	t _{ONMIN}	0.3	0.7	1.2	μs	R=39kΩ, C=1000pF

○ Package outline



HTSSOP-B24 (Unit: mm)

○ Block diagram



○ Pin No. / Pin name

Pin No.	Pin name	Pin No.	Pin name
1	PGND	13	IN1A
2	IN2B	14	PGND
3	VREF2	15	VCC1
4	CR2	16	OUT1A
5	NC	17	RNF1
6	TEST	18	OUT1B
7	GND	19	OUT2B
8	PS	20	RNF2
9	CR1	21	OUT2A
10	VREF1	22	VCC2
11	IN1B	23	NC
12	NC	24	IN2A

NC : Non Connection

○Operation Notes

- (1) Absolute maximum ratings
An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.
- (2) Power supply lines
As return of current regenerated by back EMF of motor happens, take steps such as putting capacitor between power supply and GND as an electric pathway for the regenerated current. Be sure that there is no problem with each property such as emptied capacity at lower temperature regarding electrolytic capacitor to decide capacity value. If the connected power supply does not have sufficient current absorption capacity, regenerative current will cause the voltage on the power supply line to rise, which combined with the product and its peripheral circuitry may exceed the absolute maximum ratings. It is recommended to implement a physical safety measure such as the insertion of a voltage clamp diode between the power supply and GND pins.
- (3) GND potential
The potential of GND pin must be minimum potential in all operating conditions.
- (4) Metal on the backside (Define the side where product markings are printed as front)
The metal on the backside is shorted with the backside of IC chip therefore it should be connected to GND. Be aware that there is a possibility of malfunction or destruction if it is shorted with any potential other than GND.
- (5) Thermal design
Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions. This IC exposes its frame of the backside of package. Note that this part is assumed to use after providing heat dissipation treatment to improve heat dissipation efficiency. Try to occupy as wide as possible with heat dissipation pattern not only on the board surface but also the backside.
- (6) Actions in strong electromagnetic field
Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.
- (7) ASO
When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO.
- (8) Thermal shutdown circuit
The IC has a built-in thermal shutdown circuit (TSD circuit). If the chip temperature becomes $T_{jmax}=150^{\circ}\text{C}$, and higher, coil output to the motor will be open. The TSD circuit is designed only to shut the IC off to prevent runaway thermal operation. It is not designed to protect or indemnify peripheral equipment. Do not use the TSD function to protect peripheral equipment.
- (9) Ground Wiring Pattern
When using both large current and small signal GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.
- (10) Mounting errors and Inter-pin short
When attaching to a printed circuit board, pay attention to the direction of the IC and displacement. Improper attachment may lead to destruction of the IC. There is also possibility of destruction from short circuits which can be caused by foreign matter entering between outputs or an output and the power supply or GND.
- (11) TEST pin
Be sure to connect TEST pin to GND.

Notes

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